

## 74ABT2244

### Octal Buffer/Line Driver with 25Ω Series Resistors in the Outputs

#### General Description

The ABT2244 is an octal buffer and line driver designed to drive the capacitive inputs of MOS memory drivers, address drivers, clock drivers, and bus-oriented transmitters/receivers.

The 25Ω series resistors in the outputs reduce ringing and eliminate the need for external resistors.

#### Features

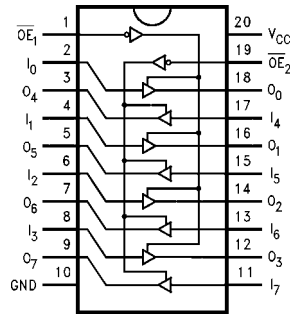
- Guaranteed latchup protection
- High impedance glitch-free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability

#### Ordering Code:

Order Number	Package Number	Package Description
74ABT2244CSC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ABT2244CSJ	M20D	Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT2244CMSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74ABT2244CMTc	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ABT2244CPC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices are also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.  
Pb-Free package per JEDEC J-STD-020B.

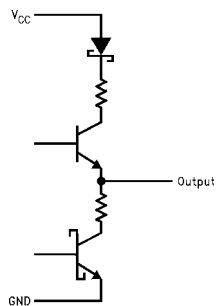
#### Connection Diagram



#### Pin Descriptions

Pin Names	Description
$\overline{OE}_1, \overline{OE}_2$	Output Enable Input (Active LOW)
$I_0-I_7$	Inputs
$O_0-O_7$	Outputs

#### Schematic of Each Output



#### Truth Table

$\overline{OE}_1$	$I_{0-3}$	$O_{0-3}$	$\overline{OE}_2$	$I_{4-7}$	$O_{4-7}$
H	X	Z	H	X	Z
L	H	H	L	H	H
L	L	L	L	L	L

H = HIGH Voltage Level  
L = LOW Voltage Level  
X = Immaterial  
Z = High Impedance

**Absolute Maximum Ratings** (Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Any Output in the Disabled or Power-off State	-0.5V to 5.5V
in the HIGH State	-0.5V to V <sub>CC</sub>
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)
DC Latchup Source Current (Across Comm Operating Range)	-300 mA
Over Voltage Latchup (I/O)	10V

**Recommended Operating Conditions**

Free Air Ambient Temperature	-40°C to +85°C
Supply Voltage	+4.5V to +5.5V
Minimum Input Edge Rate ( $\Delta V/\Delta t$ )	
Data Input	50 mV/ns
Enable Input	20 mV/ns

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH	2.5			V	Min	I <sub>OH</sub> = -3 mA
		2.0			V	Min	I <sub>OH</sub> = -32 mA
V <sub>OL</sub>	Output LOW Voltage		0.8		V	Min	I <sub>OL</sub> = 15 mA
I <sub>IH</sub>	Input HIGH Current		1		μA	Max	V <sub>IN</sub> = 2.7V (Note 4)
			1		μA	Max	V <sub>IN</sub> = V <sub>CC</sub>
I <sub>BVI</sub>	Input HIGH Current Breakdown Test			7	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>IL</sub>	Input LOW Current			-1	μA	Max	V <sub>IN</sub> = 0.5V (Note 4)
				-1	μA	Max	V <sub>IN</sub> = 0.0V
V <sub>ID</sub>	Input Leakage Test	475			V	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded
I <sub>OZH</sub>	Output Leakage Current			10	μA	0 - 5.5V	V <sub>OUT</sub> = 2.7V; $\overline{OE}n = 2.0V$
I <sub>OZL</sub>	Output Leakage Current			-10	μA	0 - 5.5V	V <sub>OUT</sub> = 0.5V; $\overline{OE}n = 2.0V$
I <sub>OS</sub>	Output Short-Circuit Current	-100		-275	mA	Max	V <sub>OUT</sub> = 0.0V
I <sub>CEX</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
I <sub>ZZ</sub>	Bus Drainage Test			100	μA	0.0	V <sub>OUT</sub> = 5.5V; All Others GND
I <sub>CCH</sub>	Power Supply Current			50	μA	Max	All Outputs HIGH
I <sub>CCL</sub>	Power Supply Current			30	mA	Max	All Outputs LOW
I <sub>CCZ</sub>	Power Supply Current			50	μA	Max	$\overline{OE}n = V_{CC}$ All Others at V <sub>CC</sub> or GND
				50	μA	Max	$\overline{OE}n = V_{CC}$ All Others at V <sub>CC</sub> or GND
I <sub>CCT</sub>	Additional I <sub>CC</sub> /Input	Outputs Enabled		2.5	mA		V <sub>I</sub> = V <sub>CC</sub> - 2.1V
		Outputs 3-STATE		2.5	mA	Max	Enable Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V
		Outputs 3-STATE		50	μA		Data Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V All Others at V <sub>CC</sub> or GND
I <sub>CCD</sub>	Dynamic I <sub>CC</sub> (Note 4)	No Load		0.1	mA/ MHz	Max	Outputs OPEN $\overline{OE}n = GND$ (Note 3) One Bit Toggling, 50% Duty Cycle

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**Note 3:** For 8 bits toggling, I<sub>CCD</sub> < 0.8 mA/MHz.

**Note 4:** Guaranteed, but not tested.

**AC Electrical Characteristics**

(SOIC and SSOP Package)

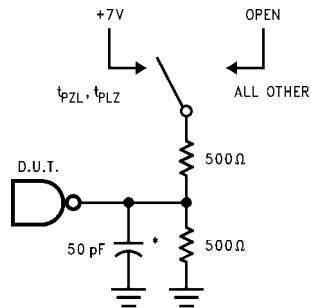
Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5\text{V}$ $C_L = 50\text{ pF}$			$T_A = -40^\circ\text{C to } +85^\circ\text{C}$ $V_{CC} = 4.5\text{V} - 5.5\text{V}$ $C_L = 50\text{ pF}$		Units
		Min	Typ	Max	Min	Max	
$t_{PLH}$	Propagation	1.0	2.2	3.9	1.0	3.9	ns
$t_{PHL}$	Delay Data to Outputs	1.0	2.9	4.4	1.0	4.4	
$t_{PZH}$	Output Enable	1.5	3.7	6.0	1.5	6.0	ns
$t_{PZL}$	Time	2.1	4.3	7.0	2.1	7.0	
$t_{PHZ}$	Output Disable	1.7	3.5	5.8	1.7	5.8	ns
$t_{PLZ}$	Time	1.7	3.7	5.8	1.7	5.8	

**Capacitance**

Symbol	Parameter	Typ	Units	Conditions $T_A = 25^\circ\text{C}$
$C_{IN}$	Input Capacitance	5.0	pF	$V_{CC} = 0\text{V}$
$C_{OUT}$ (Note 5)	Output Capacitance	9.0	pF	$V_{CC} = 5.0\text{V}$

**Note 5:**  $C_{OUT}$  is measured at frequency  $f = 1\text{ MHz}$ , per MIL-STD-883, Method 3012.

### AC Loading



\*Includes jig and probe capacitance

FIGURE 1. Standard AC Test Load

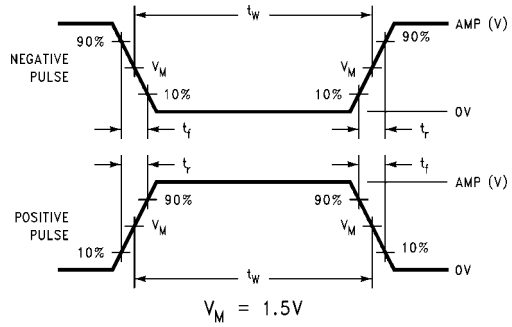


FIGURE 2. Test Input Signal Levels

Amplitude	Rep. Rate	$t_w$	$t_r$	$t_f$
3.0V	1 MHz	500 ns	2.5 ns	2.5 ns

FIGURE 3. Test Input Signal Requirements

### AC Waveforms

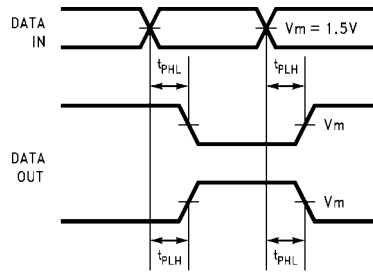


FIGURE 4. Propagation Delay Waveforms for Inverting and Non-Inverting Functions

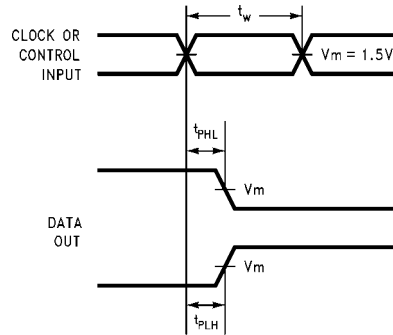


FIGURE 6. Propagation Delay, Pulse Width Waveforms

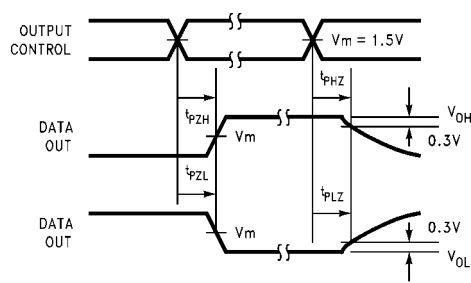


FIGURE 5. 3-STATE Output HIGH and LOW Enable and Disable Times

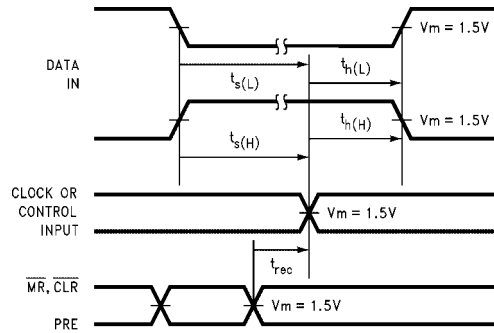
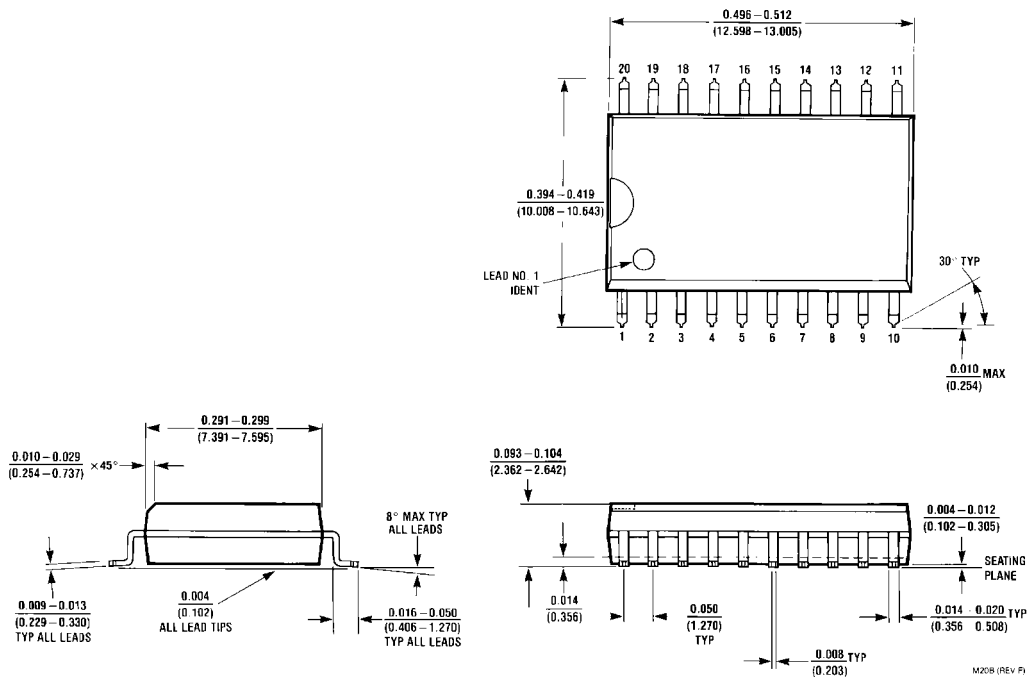


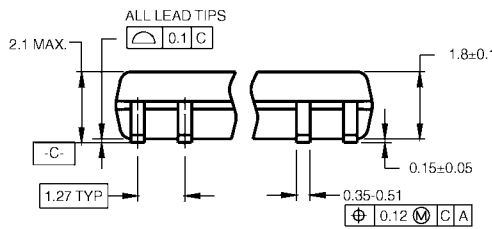
FIGURE 7. Setup Time, Hold Time and Recovery Time Waveforms

**Physical Dimensions** inches (millimeters) unless otherwise noted

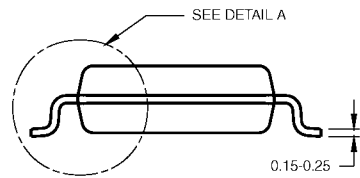


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide  
Package Number M20B**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS



- NOTES:  
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

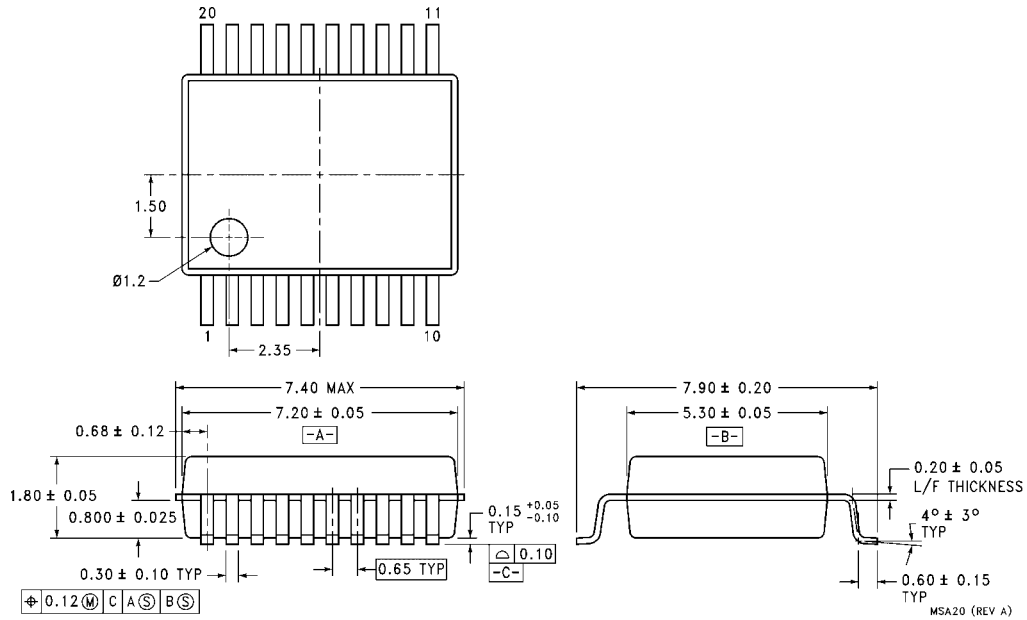
M20DRevB1



DETAIL A

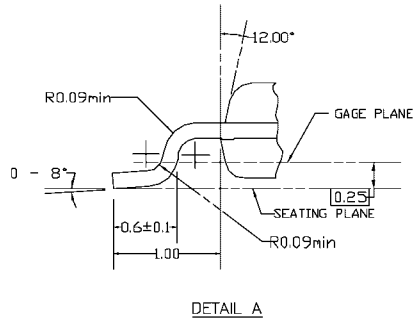
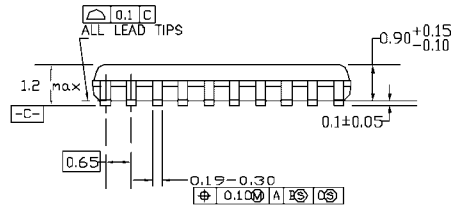
**Pb-Free 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide  
 Package Number MSA20**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

NOTES:

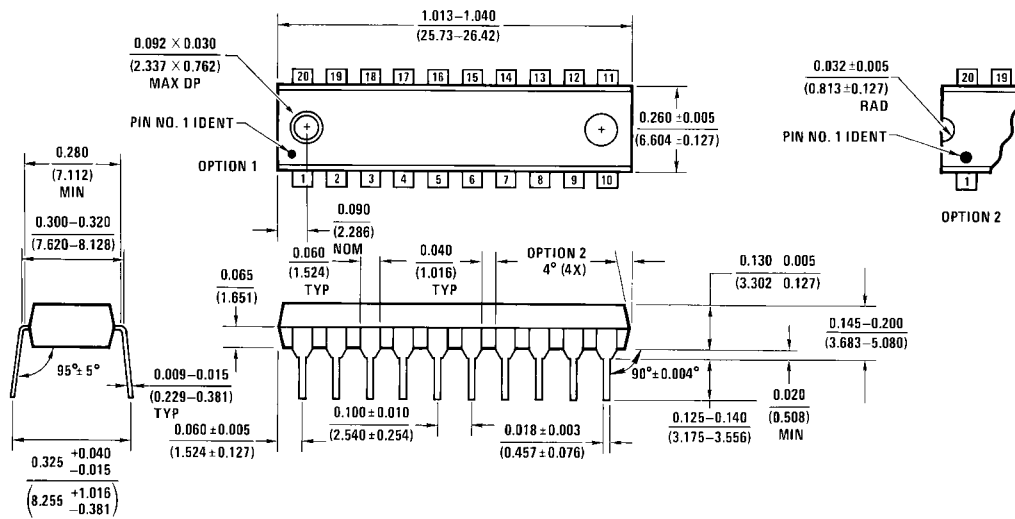
- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AC, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC20REV D1

**20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide  
Package Number MTC20**



**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



N20A (REV G)

**20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide  
Package Number N20A**

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